Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.025”**

**ANODE**

**.025”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .006 X .006”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .025” X .025” DATE: 11/10/21**

**MFG: KNOX / AEROFLEX THICKNESS .005 - .012” P/N: 1N5314**

**DG 10.1.2**

#### Rev B, 7/1